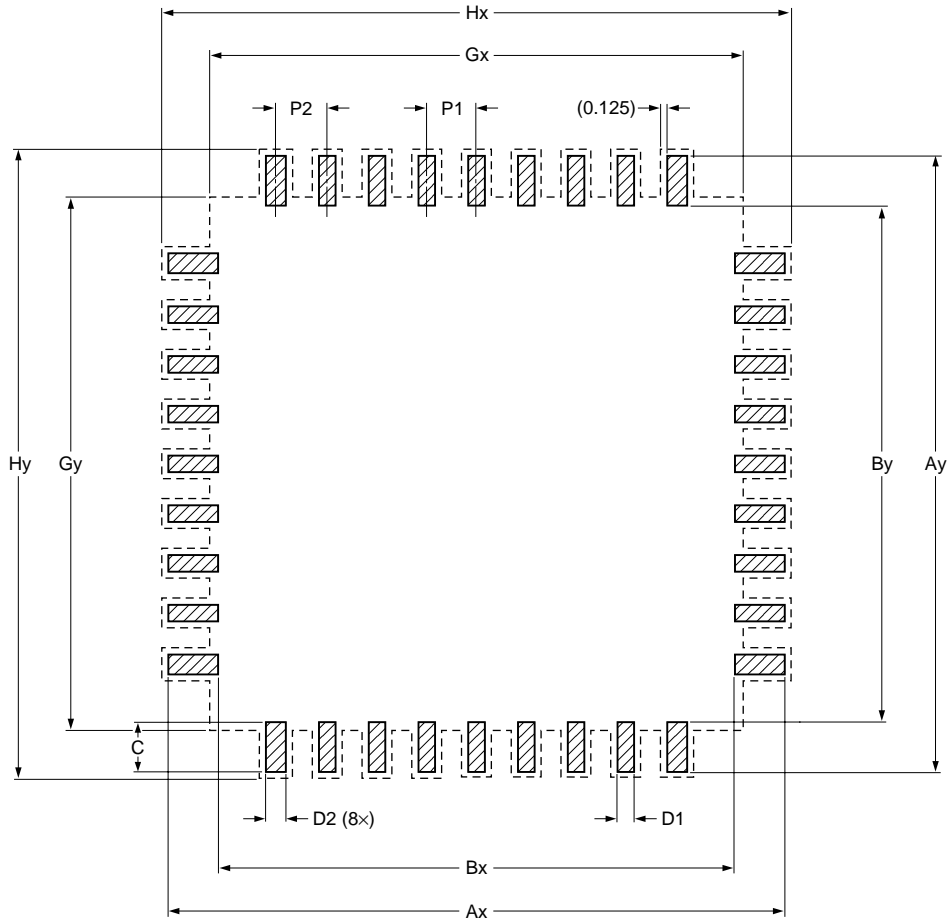



Footprint information for reflow soldering of LQFP44 package

SOT389-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
 - - - - occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.800	0.850	13.300	13.300	10.300	10.300	1.500	0.500	0.600	10.500	10.500	13.550	13.550